

Revision History
AS7C34098B

Revision	Details	Date
Rev 1.0	Initial Issue	Aug. 2016
Rev 2.0	Add TFBGA package	June. 2017

256K X 16 BIT HIGH SPEED CMOS SRAM

FEATURES

- Fast access time : 10ns ■
- **Low power consumption:**
 - Operating current:
40mA (TYP.)
 - Standby current:
2mA (TYP.)
- Single 3.3V power supply
- All inputs and outputs TTL compatible
- Fully static operation
- Tri-state output
- Data byte control : LB# (DQ0 ~ DQ7)
UB# (DQ8 ~ DQ15)
- Data retention voltage : 1.5V (MIN.)
- **ROHS compliant**
- Package : 44-pin 400mil TSOP II
48-ball 6mm x 8mm TFBGA

GENERAL DESCRIPTION

The AS7C34098B is a 4,194,304-bit high speed CMOS static random access memory organized as 262,144 words by 16 bits. It is fabricated using very high performance, high reliability CMOS technology. Its standby current is stable within the range of operating temperature.

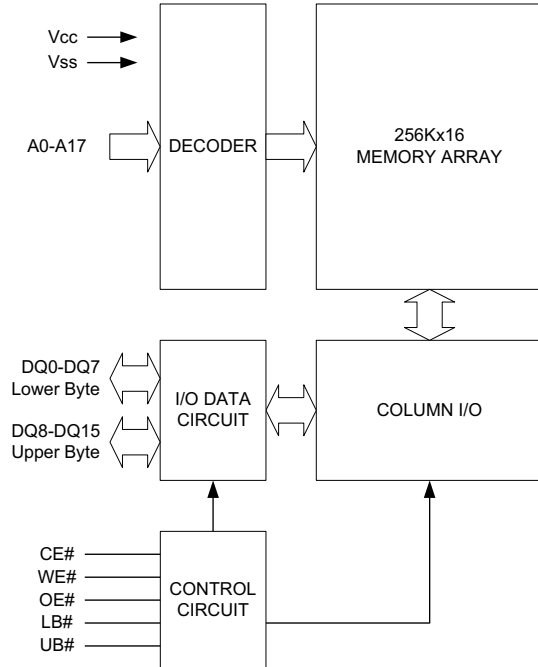
The AS7C34098B operates from a single power supply of 3.3V and all inputs and outputs are fully TTL compatible

Table 1. Ordering Information

Part Number	Speed	Temperature	Vcc Range	Package
AS7C34098B-10TIN*	10ns	Industrial -40°C to +85°C	2.7 ~ 3.6V	44pin TSOPII
AS7C34098B-10BIN*	10ns	Industrial -40°C to +85°C	2.7 ~ 3.6V	48-ball TFBGA

* : indicates Tray and add TR =Tape Reel packing type

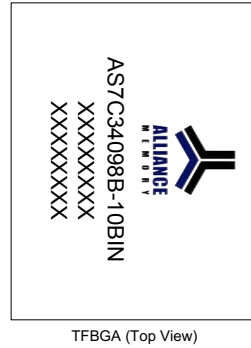
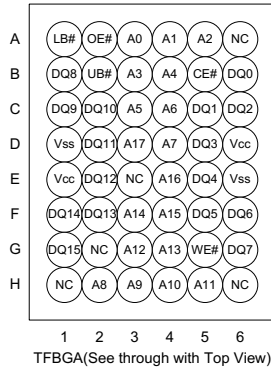
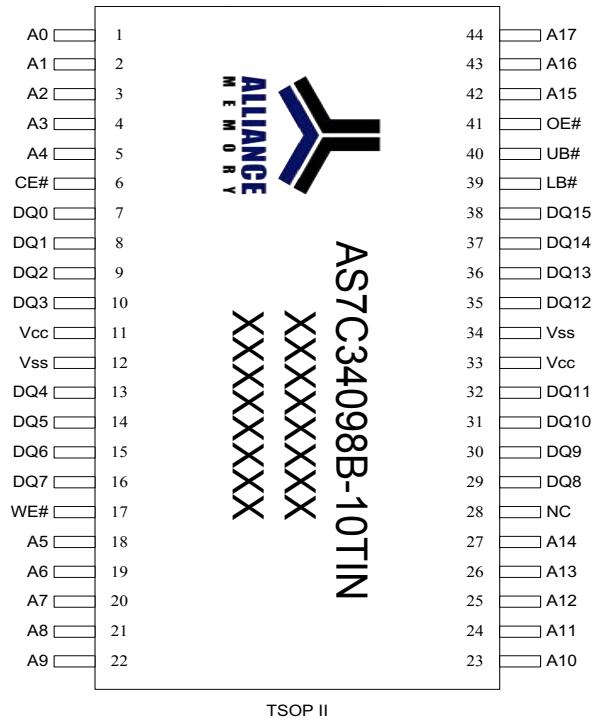
FUNCTIONAL BLOCK DIAGRAM



SYMBOL	DESCRIPTION
A0 - A17	Address Inputs
DQ0 - DQ15	Data Inputs/Outputs
CE#	Chip Enable Inputs
WE#	Write Enable Input
OE#	Output Enable Input
LB#	Lower Byte Control
UB#	Upper Byte Control
V _{cc}	Power Supply
V _{ss}	Ground
NC	No Connection

PIN DESCRIPTION

PIN CONFIGURATION



ABSOLUTE MAXIMUM RATINGS*

PARAMETER	SYMBOL	RATING	UNIT
Voltage on V_{CC} relative to V_{SS}	V_{T1}	-0.5 to 4.6	V
Voltage on any other pin relative to V_{SS}	V_{T2}	-0.5 to $V_{CC}+0.5$	V
Operating Temperature	T_A	-40 to 85	°C
Storage Temperature	T_{STG}	-65 to 150	°C
Power Dissipation	P_D	1	W
DC Output Current	I_{OUT}	50	mA

*Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to the absolute maximum rating conditions for extended period may affect device reliability.

TRUTH TABLE

MODE	CE#	OE#	WE#	LB#	UB#	I/O OPERATION		SUPPLY CURRENT
						DQ0 - DQ7	DQ8 - DQ15	
Standby	H	X	X	X	X	High-Z	High-Z	I_{SB}, I_{SB1}
Output Disable	L	H	H	X	X	High-Z	High-Z	I_{CC}, I_{CC1}
	L	X	X	H	H	High-Z	High-Z	
Read	L	L	H	L	H	D_{OUT}	High-Z	I_{CC}, I_{CC1}
	L	L	H	H	L	High-Z	D_{OUT}	
	L	L	H	L	L	D_{OUT}	D_{OUT}	
Write	L	X	L	L	H	D_{IN}	High-Z	I_{CC}, I_{CC1}
	L	X	L	H	L	High-Z	D_{IN}	
	L	X	L	L	L	D_{IN}	D_{IN}	

Note: H = V_{IH} , L = V_{IL} , X = Don't care

DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP. ^{*4}	MAX.	UNIT
Supply Voltage	V_{CC}		2.7	3.3	3.6	V
Input High Voltage	V_{IH}^{*1}		2.2	-	$V_{CC}+0.3$	V
Input Low Voltage	V_{IL}^{*2}		- 0.3	-	0.8	V
Input Leakage Current	I_{LI}	$V_{CC} \geq V_{IN} \geq V_{SS}$	- 1	-	1	μA
Output Leakage Current	I_{LO}	$V_{CC} \geq V_{OUT} \geq V_{SS}$, Output Disabled	- 1	-	1	μA
Output High Voltage	V_{OH}	$I_{OH} = -4mA$	2.4	-	-	V
Output Low Voltage	V_{OL}	$I_{OL} = 8mA$	-	-	0.4	V
Average Operating Power supply Current	I_{CC}	Cycle time = MIN. $CE\# = V_{IL}$, $I_{I/O} = 0mA$, Others at V_{IL} or V_{IH}	-	50	70	mA
	I_{CC1}	$CE\# \leq 0.2$, Others at 0.2V or $V_{CC}-0.2V$ $I_{I/O} = 0mA$; $f=MAX.$	-	40	55	mA
Standby Power Supply Current	I_{SB}	$CE\# = V_{IH}$, Others at V_{IL} or V_{IH}	-	-	30	mA
	I_{SB1}	$CE\# \geq V_{CC} - 0.2V$, Others at 0.2V or $V_{CC} - 0.2V$	-	2	10	mA

Notes:

- $V_{IH}(max) = V_{CC} + 2.0V$ for pulse width less than 6ns.
- $V_{IL}(min) = V_{SS} - 2.0V$ for pulse width less than 6ns.
- Over/Undershoot specifications are characterized on engineering evaluation stage, not for mass production test.
- Typical values are included for reference only and are not guaranteed or tested.
Typical values are measured at $V_{CC} = V_{CC}(TYP.)$ and $T_A = 25^\circ C$

CAPACITANCE ($T_A = 25^\circ C$, $f = 1.0MHz$)

PARAMETER	SYMBOL	MIN.	MAX.	UNIT
Input Capacitance	C_{IN}	-	8	pF
Input/Output Capacitance	$C_{I/O}$	-	10	pF

Note : These parameters are guaranteed by device characterization, but not production tested.

AC TEST CONDITIONS

Speed	10ns
Input Pulse Levels	0.2V to $V_{CC} - 0.2V$
Input Rise and Fall Times	3ns
Input and Output Timing Reference Levels	1.5V
Output Load	$C_L = 30pF + 1TTL$, $I_{OH}/I_{OL} = -4mA/8mA$

AC ELECTRICAL CHARACTERISTICS

(1) READ CYCLE

PARAMETER	SYM.	AS7C34098B-10		UNIT
		MIN.	MAX.	
Read Cycle Time	t_{RC}	10	-	ns
Address Access Time	t_{AA}	-	10	ns
Chip Enable Access Time	t_{ACE}	-	10	ns
Output Enable Access Time	t_{OE}	-	4.5	ns
Chip Enable to Output in Low-Z	t_{CLZ}^*	2	-	ns
Output Enable to Output in Low-Z	t_{OLZ}^*	0	-	ns
Chip Disable to Output in High-Z	t_{CHZ}^*	-	4	ns
Output Disable to Output in High-Z	t_{OHZ}^*	-	4	ns
Output Hold from Address Change	t_{OH}	2	-	ns
LB#, UB# Access Time	t_{BA}	-	4.5	ns
LB#, UB# to High-Z Output	t_{BHZ}^*	-	4	ns
LB#, UB# to Low-Z Output	t_{BLZ}^*	0	-	ns

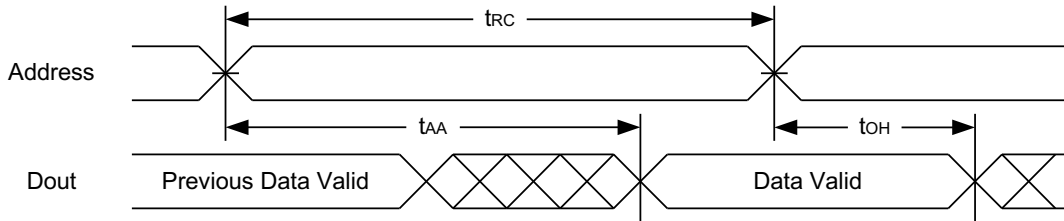
(2) WRITE CYCLE

PARAMETER	SYM.	AS7C34098B-10		UNIT
		MIN.	MAX.	
Write Cycle Time	t_{WC}	10	-	ns
Address Valid to End of Write	t_{AW}	8	-	ns
Chip Enable to End of Write	t_{CW}	8	-	ns
Address Set-up Time	t_{AS}	0	-	ns
Write Pulse Width	t_{WP}	8	-	ns
Write Recovery Time	t_{WR}	0	-	ns
Data to Write Time Overlap	t_{DW}	6	-	ns
Data Hold from End of Write Time	t_{DH}	0	-	ns
Output Active from End of Write	t_{OW}^*	2	-	ns
Write to Output in High-Z	t_{WHZ}^*	-	4	ns
LB#, UB# Valid to End of Write	t_{BW}	8	-	ns

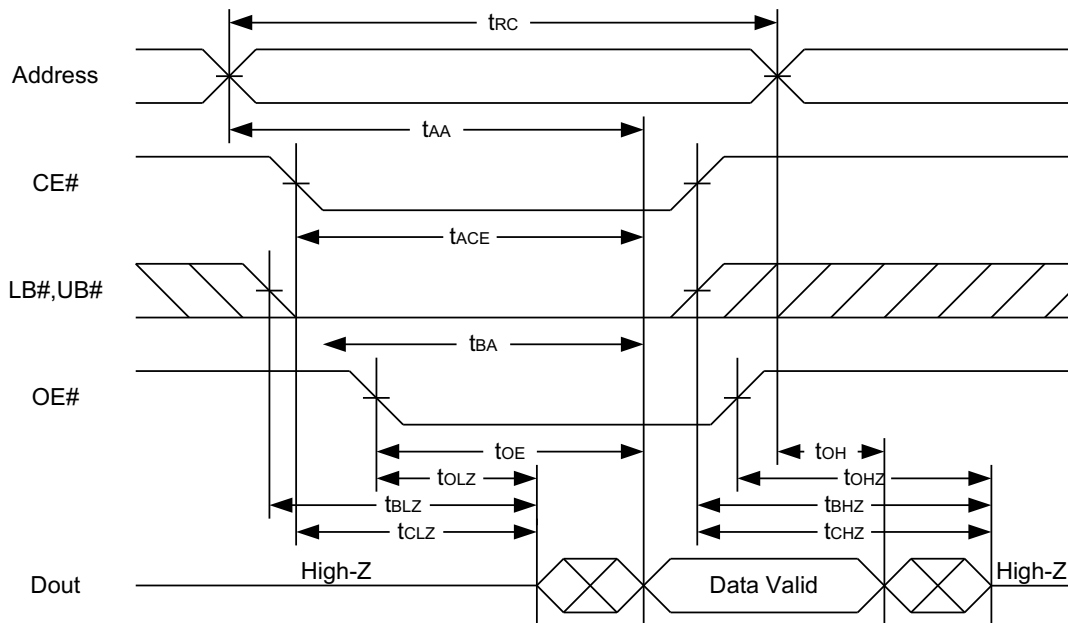
*These parameters are guaranteed by device characterization, but not production tested.

TIMING WAVEFORMS

READ CYCLE 1 (Address Controlled) (1,2)



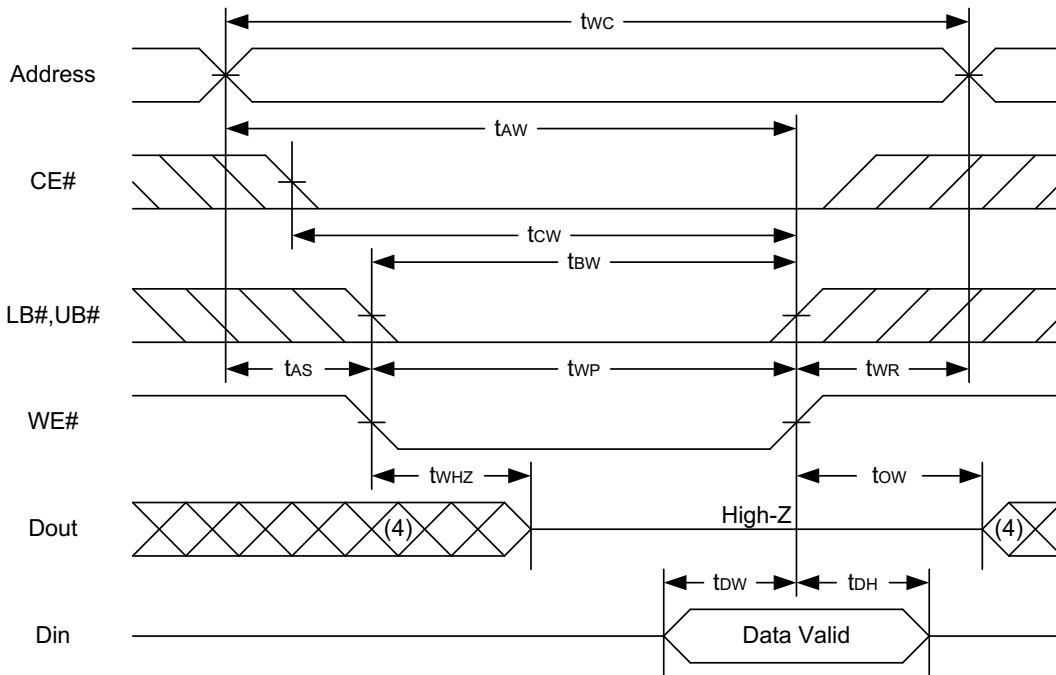
READ CYCLE 2 (CE# and OE# Controlled) (1,3,4,5)



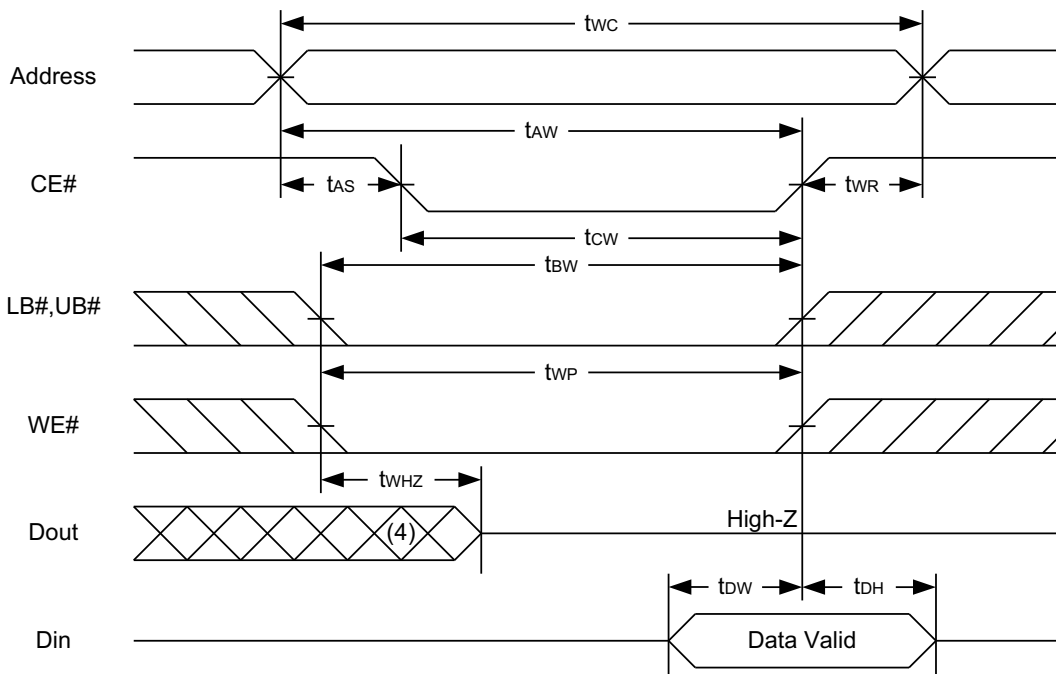
Notes :

1. WE# is high for read cycle.
2. Device is continuously selected OE# = low, CE# = low, LB# or UB# = low.
3. Address must be valid prior to or coincident with CE# = low, LB# or UB# = low transition; otherwise t_{AA} is the limiting parameter.
4. t_{CLZ} , t_{BLZ} , t_{OLZ} , t_{CHZ} , t_{BHZ} and t_{OHZ} are specified with $C_L = 5\text{pF}$. Transition is measured $\pm 500\text{mV}$ from steady state.
5. At any given temperature and voltage condition, t_{CHZ} is less than t_{CLZ} , t_{BHZ} is less than t_{BLZ} , t_{OHZ} is less than t_{OLZ}

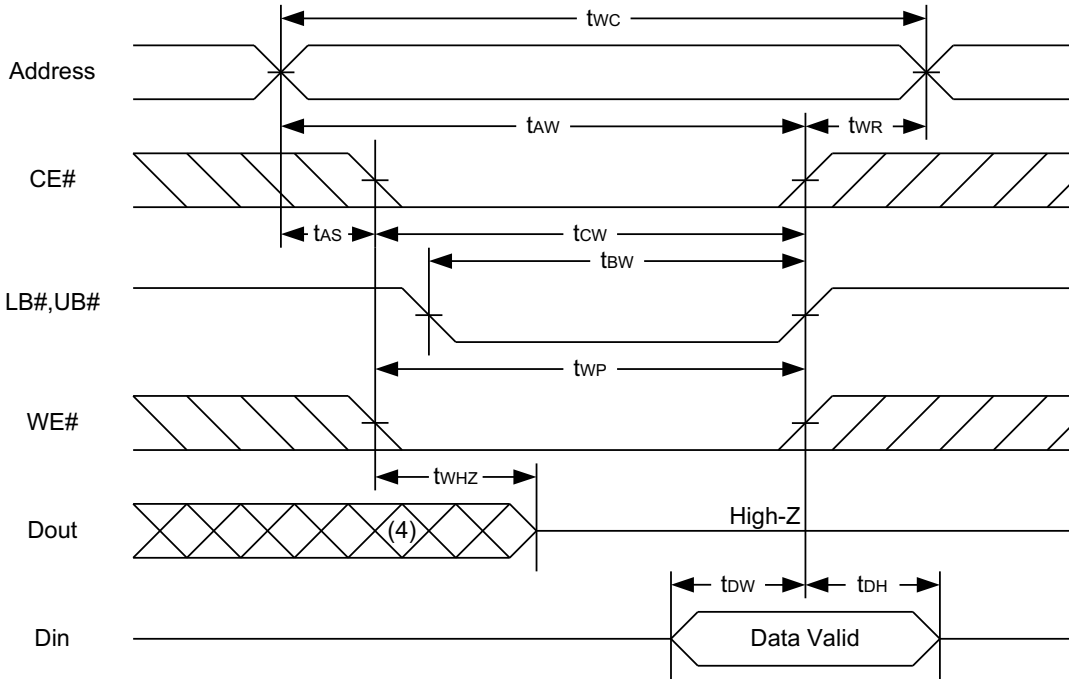
WRITE CYCLE 1 (WE# Controlled) (1,2,4,5)



WRITE CYCLE 2 (CE# Controlled) (1,4,5)



WRITE CYCLE 3 (LB#,UB# Controlled) (1,4,5)



Notes :

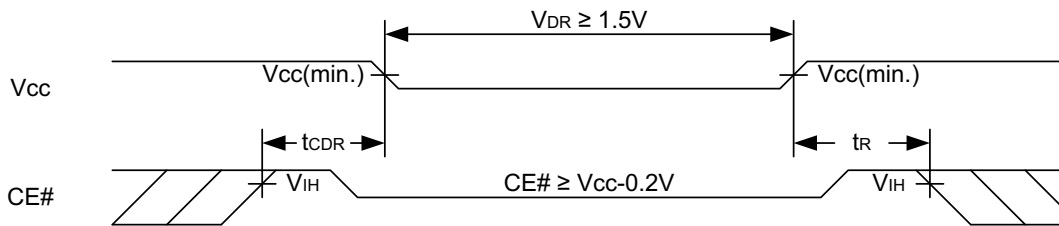
1. A write occurs during the overlap of a low CE#, low WE#, LB# or UB# = low.
2. During a WE# controlled write cycle with OE# low, t_{WP} must be greater than $t_{WHZ} + t_{DW}$ to allow the drivers to turn off and data to be placed on the bus.
3. During this period, I/O pins are in the output state, and input signals must not be applied.
4. If the CE#, LB#, UB# low transition occurs simultaneously with or after WE# low transition, the outputs remain in a high impedance state.
5. t_{DW} and t_{WHZ} are specified with $C_L = 5\text{pF}$. Transition is measured $\pm 500\text{mV}$ from steady state.

DATA RETENTION CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
V _{CC} for Data Retention	V _{DR}	CE# \geq V _{CC} - 0.2V	1.5	-	3.6	V
Data Retention Current	I _{DR}	V _{CC} = 1.5V, CE# \geq V _{CC} - 0.2V Others at 0.2V or V _{CC} - 0.2V	-	2	10	mA
Chip Disable to Data Retention Time	t _{CDR}	See Data Retention Waveforms (below)	0	-	-	ns
Recovery Time	t _R		t _{RC} *	-	-	ns

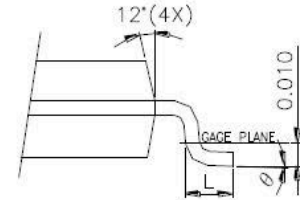
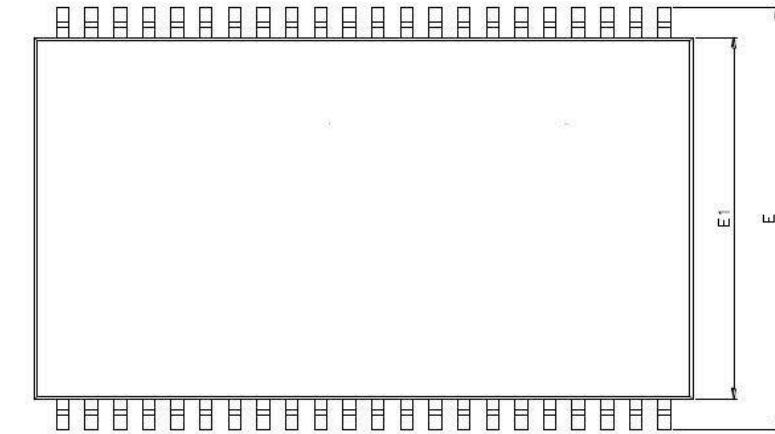
t_{RC}* = Read Cycle Time

DATA RETENTION WAVEFORM

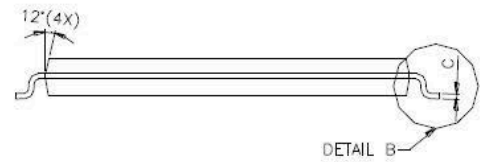
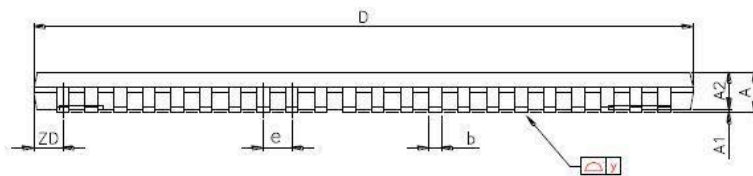


PACKAGE OUTLINE DIMENSION

44-pin 400 mil TSOP II Package Outline Dimension



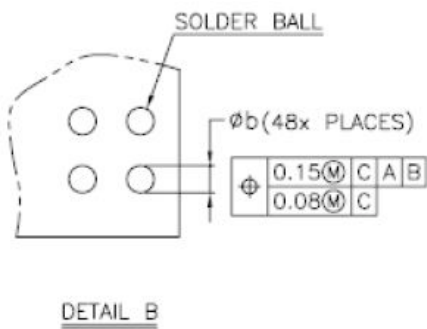
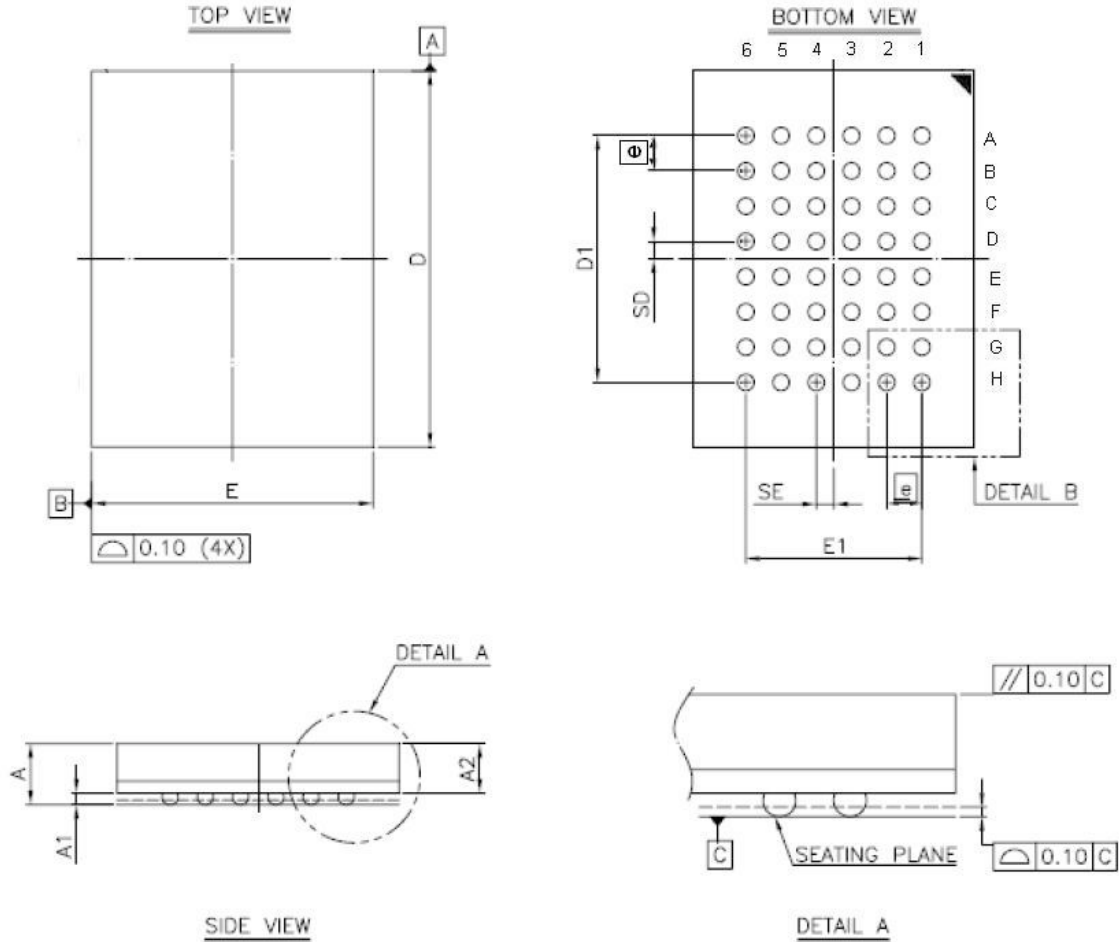
DETAIL B



DETAIL B

SYMBOLS	DIMENSIONS IN MILLMETERS			DIMENSIONS IN MILS		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	-	-	1.20	-	-	47.2
A1	0.05	0.10	0.15	2.0	3.9	5.9
A2	0.95	1.00	1.05	37.4	39.4	41.3
b	0.30	-	0.45	11.8	-	17.7
c	0.12	-	0.21	4.7	-	8.3
D	18.212	18.415	18.618	717	725	733
E	11.506	11.760	12.014	453	463	473
E1	9.957	10.160	10.363	392	400	408
e	-	0.800	-	-	31.5	-
L	0.40	0.50	0.60	15.7	19.7	23.6
ZD	-	0.805	-	-	31.7	-
y	-	-	0.076	-	-	3
θ	0°	3°	6°	0°	3°	6°

48-ball 6mm × 8mm TFBGA Package Outline Dimension



SYM.	DIMENSION (mm)			DIMENSION (inch)		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	—	—	1.40	—	—	0.055
A1	0.20	0.25	0.30	0.008	0.010	0.012
A2	—	—	1.05	—	—	0.041
b	0.30	0.35	0.40	0.012	0.014	0.016
D	7.95	8.00	8.05	0.313	0.315	0.317
D1	5.25 BSC			0.207 BSC		
E	5.95	6.00	6.05	0.234	0.236	0.238
E1	3.75 BSC			0.148 BSC		
SE	0.375 TYP			0.015 TYP		
SD	0.375 TYP			0.015 TYP		
□	0.75 BSC			0.030 BSC		

NOTE:

1. CONTROLLING DIMENSION : MILLIMETER.
2. REFERENCE DOCUMENT : JEDEC MO-207.

ORDERING INFORMATION

Package Type	Access Time (Speed/ns)	Temperature Range(°C)	Packing Type	Alliance Memory Part Number
44-pin (400mil) TSOP II	10	-40°C~85°C	Tray	AS7C34098B-10TIN
			Tape Reel	AS7C34098B-10TINTR
48-ball (6mm x 8mm) TFBGA	10	-40°C~85°C	Tray	AS7C34098B-10BIN
			Tape Reel	AS7C34098B-10BINTR



Alliance Memory, Inc.
 511 Taylor Way,
 San Carlos, CA 94070
 Tel: 650-610-6800
 Fax: 650-620-9211
www.alliancememory.com

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